



TECHNICAL REPORT



**Dynamic modules –
Part 6-5: Design guide – Investigation of operating mechanical shock and
vibration tests for dynamic modules**

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IEC 62343-6-5, which is a technical report, has been prepared by subcommittee 86C: Fibre optic systems and active devices, of IEC technical committee 86: Fibre optics.

This second edition cancels and replaces the first edition published in 2011. It constitutes technical revision.

The main change with respect to the previous edition is the addition of "Results of a questionnaire on dynamic module operating shock and vibration test conditions" in Annex A.

The text of this technical report is based on the following documents:

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86C/1206/DTR	86C/1246/RVC

Full information on the voting for the approval of this technical report can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts of IEC 62343 series, published under the general title *Dynamic modules*, can be found on the IEC website.

The committee has decided that the contents of this publication will remain unchanged until the stability date indicated on the IEC web site under "<http://webstore.iec.ch>" in the data related to the specific publication. At this date, the publication will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

A bilingual version of this publication may be issued at a later date.

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DYNAMIC MODULES –

Part 6-5: Design guide – Investigation of operating mechanical shock and vibration tests for dynamic modules

1 Scope

This part of IEC 62343, which is a technical report, describes an investigation into operating mechanical shock and vibration for dynamic modules. It also presents the results of a survey on the evaluation and mechanical simulation of mechanical shock and vibration testing. Also included is a study of standardization for operating mechanical shock and vibration test methods.